SCAS234B - JULY 1990 - REVISED OCTOBER 1996

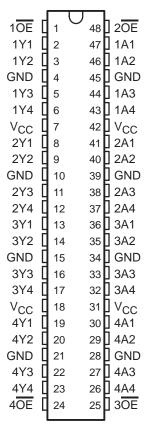
- Members of the Texas Instruments
 Widebus™ Family
- 3-State Outputs Drive Bus Lines or Buffer Memory Address Registers
- Flow-Through Architecture Optimizes PCB Layout
- Distributed V_{CC} and GND Pin Configuration Minimizes High-Speed Switching Noise
- EPIC™ (Enhanced-Performance Implanted CMOS) 1-µm Process
- 500-mA Typical Latch-Up Immunity at
- Package Options Include Plastic 300-mil Shrink Small-Outline (DL) Package Using 25-mil Center-to-Center Pin Spacings and 380-mil Fine-Pitch Ceramic Flat (WD) Package Using 25-mil Center-to-Center Pin Spacings

description

The 'AC16240 are 16-bit buffers and line drivers designed specifically to improve both the performance and density of 3-state memory address drivers, clock drivers, and bus-oriented receivers and transmitters.

They can be used as four 4-bit buffers, two 8-bit buffers, or one 16-bit buffer. These devices provide inverting outputs and symmetrical active-low output-enable (\overline{OE}) inputs.

54AC16240 ... WD PACKAGE 74AC16240 ... DL PACKAGE (TOP VIEW)



The 74AC16240 is packaged in TI's shrink small-outline package, which provides twice the I/O pin count and functionality of standard small-outline packages in the same printed circuit board area.

The 54AC16240 is characterized for operation over the full military temperature range of -55°C to 125°C.

The 74AC16240 is characterized for operation from -40°C to 85°C.

FUNCTION TABLE (each 4-bit buffer)

INP	JTS	OUTPUT
OE	Α	Y
L	Н	L
L	L	Н
Н	Χ	Z

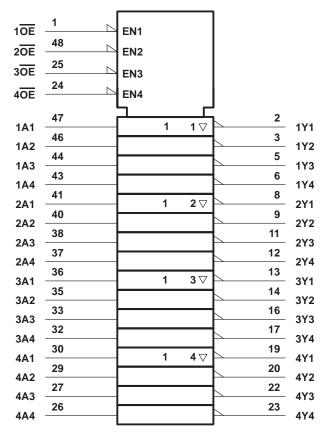


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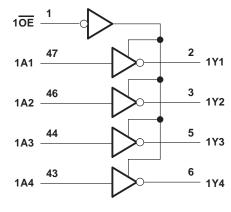
TEXAS INSTRUMENTS

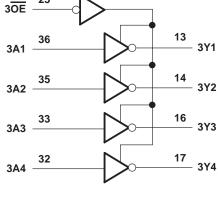
logic symbol†

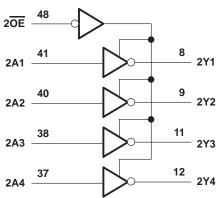


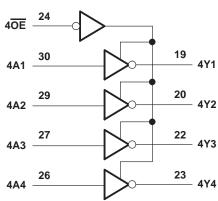
 $[\]ensuremath{^{\dagger}}$ This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)









absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V _{CC}	–0.5 V to 7 V
Input voltage range, V _I (see Note 1)	\dots -0.5 V to V _{CC} + 0.5 V
Output voltage range, V _O (see Note 1)	\dots -0.5 V to V _{CC} + 0.5 V
Input clamp current, I_{IK} ($V_I < 0$ or $V_I > V_{CC}$)	±20 mA
Output clamp current, I _{OK} (V _O < 0 or V _O > V _{CC})	±50 mA
Continuous output current, I_O ($V_O = 0$ to V_{CC})	±50 mA
Continuous current through V _{CC} or GND	±400 mA
Maximum power dissipation at $T_A = 55^{\circ}C$ (in still air)(see Note 2): DL package .	1.2 W
Storage temperature range, T _{stg}	–65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

^{2.} The maximum package power dissipation is calculated using a junction temperature of 150°C and a board trace length of 750 mils.

recommended operating conditions (see Note 3)

			54	54AC16240			AC1624	0	LINUT	
			MIN	NOM	MAX	MIN	NOM	MAX	UNIT	
VCC	Supply voltage		3	5	5.5	3	5	5.5	V	
		V _{CC} = 3 V	2.1			2.1				
ViH	High-level input voltage	V _{CC} = 4.5 V	3.15			3.15			V	
		$V_{CC} = 5.5 \text{ V}$	3.85			3.85				
V _{IL}		V _{CC} = 3 V			0.9			0.9		
	Low-level input voltage	V _{CC} = 4.5 V			1.35			1.35	V	
		V _{CC} = 5.5 V		N. A.	1.65			1.65		
VI	Input voltage		0	Q	VCC	0		VCC	V	
Vo	Output voltage		0	, ,	VCC	0		VCC	V	
		V _{CC} = 3 V	4	20	-4			-4		
IOH	High-level output current	V _{CC} = 4.5 V	W. C.	,	-24			-24	mA	
		V _{CC} = 5.5 V			-24			-24		
		VCC = 3 V			12			12		
lOL	Low-level output current	V _{CC} = 4.5 V			24			24	mA	
		V _{CC} = 5.5 V			24			24		
Δt/Δν	Input transition rise or fall rate		0		10	0		10	ns/V	
TA	Operating free-air temperature		-55		125	-40		85	°C	

NOTE 3: Unused inputs must be held high or low to prevent them from floating.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

	TEGT CONDITIONS	vcc	T,	_A = 25°C	54AC16240	74AC16240	
PARAMETER	ER TEST CONDITIONS		MIN	TYP MAX	MIN MAX	MIN MAX	UNIT
		3 V	2.9		2.9	2.9	
	I _{OH} = -50 μA	4.5 V	4.4		4.4	4.4	
		5.5 V	5.4		5.4	5.4	
Voн	$I_{OH} = -4 \text{ mA}$	3 V	2.58		2.48	2.48	V
		4.5 V	3.94		3.8	3.8	
	I _{OH} = −24 mA	5.5 V	4.94		4.8	4.8	
	$I_{OH} = -75 \text{ mA}^{\dagger}$	5.5 V			3.85	3.85	
		3 V		0.1	0.1	0.1	
	$I_{OL} = 50 \mu A$	4.5 V		0.1	6 0.1	0.1	V
		5.5 V		0.1	0.1	0.1	
VOL	I _{OL} = 12 mA	3 V		0.36	0.44	0.44	
	lo 24 mA	4.5 V		0.36	0.44	0.44	
	I _{OL} = 24 mA	5.5 V		0.36	0.44	0.44	
	$I_{OL} = 75 \text{ mA}^{\dagger}$	5.5 V			1.65	1.65	
lį	$V_I = V_{CC}$ or GND	5.5 V		±0.1	±1	±1	μΑ
loz	$V_O = V_{CC}$ or GND	5.5 V		±0.5	±5	±5	μΑ
ICC	$V_I = V_{CC}$ or GND, $I_O = 0$	5.5 V		8	80	80	μΑ
Ci	$V_I = V_{CC}$ or GND	5 V		4.5			pF
Co	$V_O = V_{CC}$ or GND	5 V		12			pF

[†] Not more than one output should be tested at a time, and the duration of the test should not exceed 10 ms.



switching characteristics over recommended operating free-air temperature range, V_{CC} = 3.3 V \pm 0.3 V (unless otherwise noted) (see Figure 1)

24244555	FROM	то	T,	4 = 25°C	;	54AC1	6240	74AC1	6240		
PARAMETER	PARAMETER (INPUT)		MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT	
^t PLH	А	V	1.8	5.4	7.5	1.8	8.3	1.8	8.3		
t _{PHL}		Y	2.5	7	9.3	2.5	10.2	2.5	10.2	ns	
^t PZH		OE Y	2.1	6.1	8.5	2.1	9.5	2.1	9.5		
^t PZL	OE		2.9	8.4	11.3	2.9	12.6	2.9	12.6	ns	
^t PHZ			ŌĒ Y	4.3	6.2	8.3	4.3	8.7	4.3	8.7	20
tPLZ	OE	ī	3.6	6	7.8	3.6	8.4	3.6	8.4	ns	

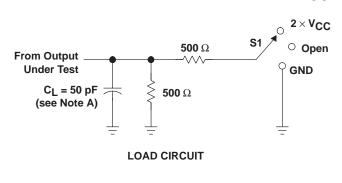
switching characteristics over recommended operating free-air temperature range, V_{CC} = 5 V \pm 0.5 V (unless otherwise noted) (see Figure 1)

24244555	FROM	то то		4 = 25°C	;	54AC1	6240	74AC1	6240	
PARAMETER	(INPUT)	(OUTPUT)	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT
^t PLH	^	V	1.3	3.3	5.3	1.3	5.8	1.3	5.8	
t _{PHL}	A	Y	1.9	4.3	6.5	1.9	7.1	1.9	7.1	ns
^t PZH		V	1.6	3.8	5.9	1.6	6.6	1.6	6.6	
t _{PZL}	OE	Y	3.2	4.7	7.2	3.2	8.1	3.2	8.1	ns
^t PHZ	ŌĒ	V	4.2	6	7.7	4.2	8.1	4.2	8.1	20
tPLZ	OE	ī	3.4	5.1	6.9	3.4	7.3	3.4	7.3	ns

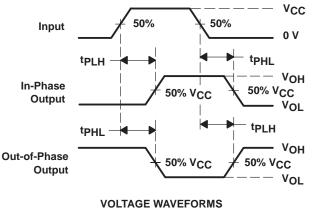
operating characteristics, V_{CC} = 5 V, T_A = 25°C

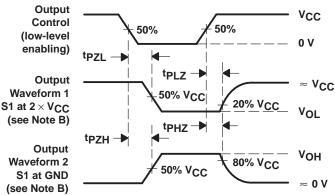
PARAMETER				TEST CONDITIONS		
C . Dawe dissination consistence nonletch	Outputs enabled	0 50 5 (4 MU)		42	pF	
Cpd	C _{pd} Power dissipation capacitance per latch	Outputs disabled	$C_L = 50 pF$,	f = 1 MHz	6	pr

PARAMETER MEASUREMENT INFORMATION



TEST	S1
tPLH/tPHL	Open
tpLZ/tpZL	2×V _{CC}
tPHZ/tPZH	GND





VOLTAGE WAVEFORMS

NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 1 MHz, $Z_O = 50 \ \Omega$, $t_f = 3 \ ns$, $t_f = 3 \ ns$.
- D. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms





PACKAGE OPTION ADDENDUM

30-Mar-2005

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
74AC16240DL	OBSOLETE	SSOP	DL	48	TBD	Call TI	Call TI
74AC16240DLR	OBSOLETE	SSOP	DL	48	TBD	Call TI	Call TI

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS) or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

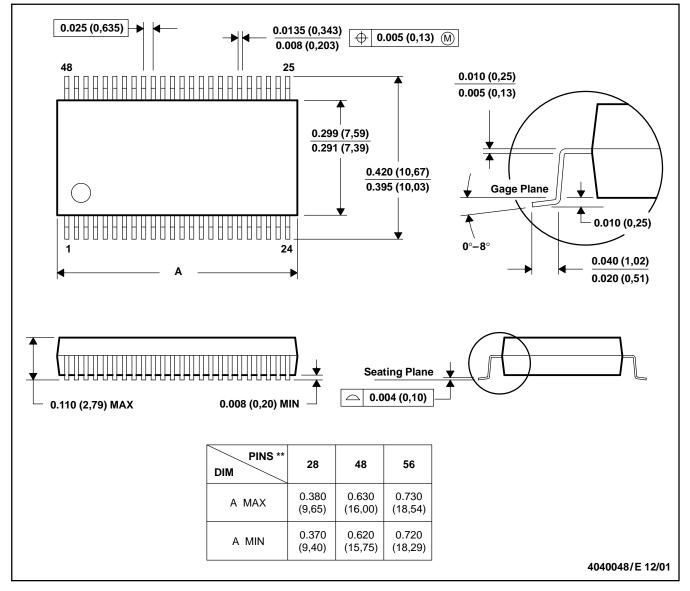
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DL (R-PDSO-G**)

48 PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).

D. Falls within JEDEC MO-118

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